

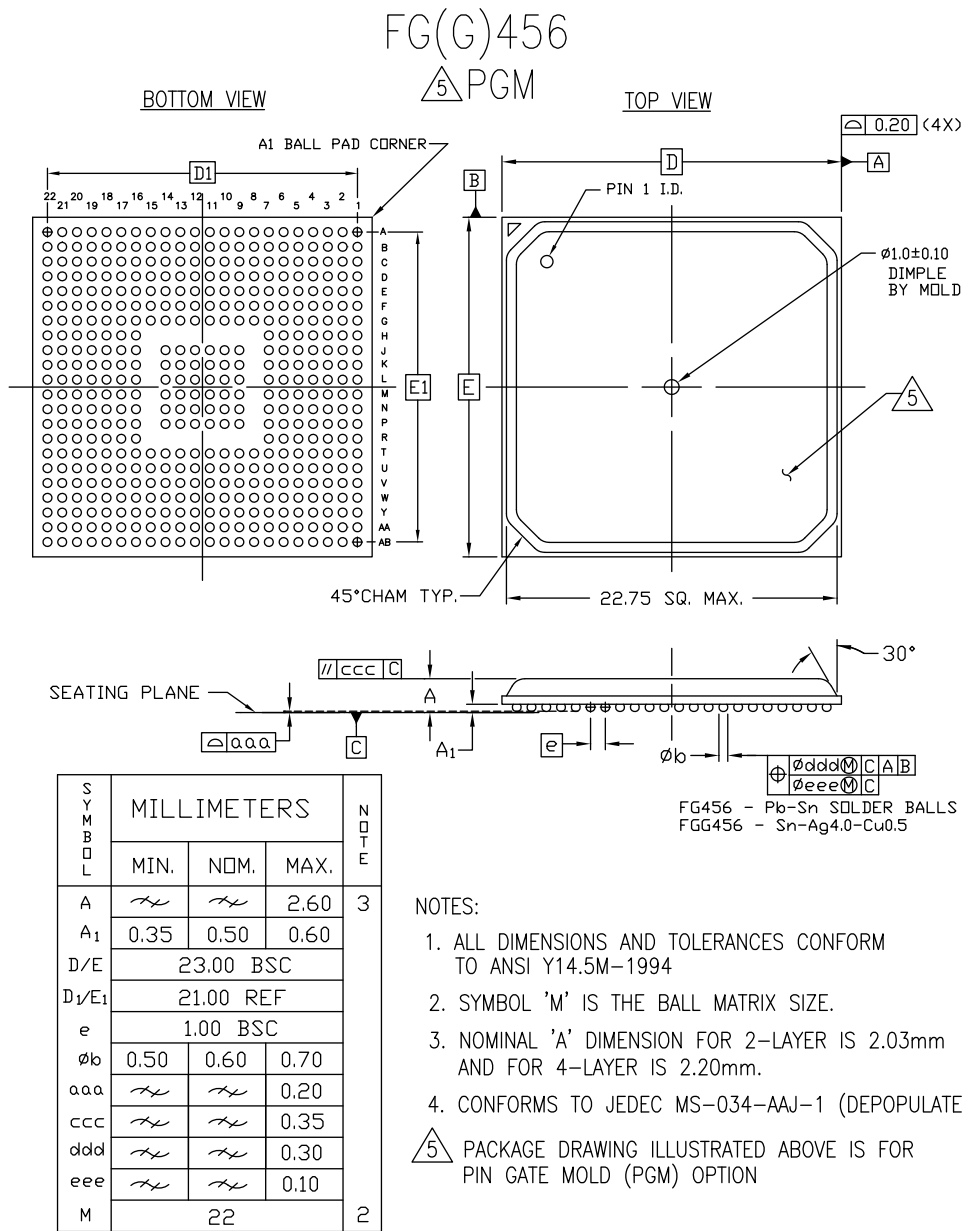
FG456 - Pb-Sn SOLDER BALLS
 FGG456 - Sn-Ag4.0-Cu0.5

SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	$\sqrt{\text{---}}$	$\sqrt{\text{---}}$	2.60	3
A ₁	0.35	0.50	0.60	
D/E	23.00 BSC			2
D ₁ /E ₁	21.00 REF			
e	1.00 BSC			
phi b	0.50	0.60	0.70	
aaa	$\sqrt{\text{---}}$	$\sqrt{\text{---}}$	0.20	
ccc	$\sqrt{\text{---}}$	$\sqrt{\text{---}}$	0.35	
ddd	$\sqrt{\text{---}}$	$\sqrt{\text{---}}$	0.30	
eee	$\sqrt{\text{---}}$	$\sqrt{\text{---}}$	0.10	
M	22			

- NOTES:
- ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
 - SYMBOL 'M' IS THE BALL MATRIX SIZE.
 - NOMINAL 'A' DIMENSION FOR 2-LAYER IS 2.03mm AND FOR 4-LAYER IS 2.20mm.
 - CONFORMS TO JEDEC MS-034-AAJ-1 (DEPOPULATED)
 - PACKAGE DRAWING ILLUSTRATED ABOVE IS FOR CORNER GATE MOLD (CGM)
 - SEE NEXT PAGE FOR PIN GATE MOLD (PGM) OPTION

pk034_01_032114

Figure 1: Corner Gate Mold Option, FG456/FGG456 Package



pk034_02_032114

Figure 2: Pin Gate Mold Option, FG456/FGG456 Package

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
04/04/2014	1.3	Added Figure 2 , pin gate mold package as described in XCN12023 .

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